SCBS199C - FEBRUARY 1991 - REVISED MAY 1997

- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- High-Impedance State During Power Up and Power Down
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW) Package, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

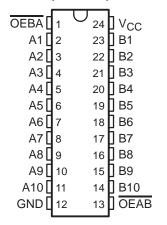
The 'ABT861 are 10-bit transceivers designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing.

These devices allow noninverted data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and OEBA) inputs.

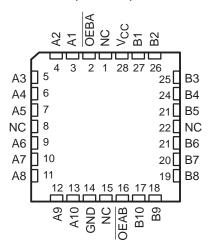
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT861 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT861 is characterized for operation from –40°C to 85°C.

SN54ABT861 . . . JT PACKAGE SN74ABT861 . . . DW OR NT PACKAGE (TOP VIEW)



SN54ABT861 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

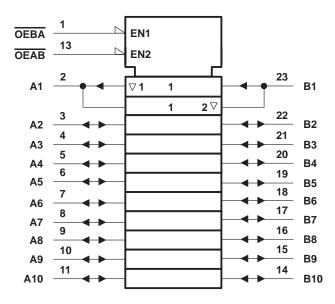
EPIC-IIB is a trademark of Texas Instruments Incorporated.



FUNCTION TABLE

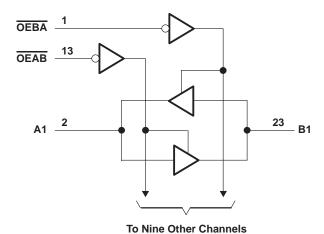
INP	UTS	ODED ATION
OEAB	OEBA	OPERATION
L	Н	A data to B bus
Н	L	B data to A bus
Н	Н	Isolation
L	L	Latch A and B (A = B)

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.

logic diagram (positive logic)



Pin numbers shown are for the DW, JT, and NT packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} –0.5	V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	V to 7 V
Voltage range applied to any output in the high or power-off state, V _O	to 5.5 V
Current into any output in the low state, IO: SN54ABT861	. 96 mA
SN74ABT861	128 mA
Input clamp current, I _{IK} (V _I < 0)	-18 mA
Output clamp current, I _{OK} (V _O < 0)	-50 mA
Package thermal impedance, θ _{JA} (see Note 2): DW package	81°C/W
NT package	67°C/W
Storage temperature range, T _{stq} –65°C	to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54AI	3T861	SN74AI	BT861	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage		2	EM	2		V
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		0 4	Vcc	0	VCC	V
IOH	High-level output current		Ç,	-24		-32	mA
loL	Low-level output current		200	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	77	5		5	ns/V
TA	Operating free-air temperature	·	– 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

SN54ABT861, SN74ABT861 10-BIT TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST COL	UDITIONS	Т	A = 25°C	;	SN54A	BT861	SN74A	BT861	UNIT
PARA	AWEIER	TEST COM	ADITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\/a		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
VOL		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V
V _{hys}					100						mV
	Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		±1		±1	μA
'I A	A or B ports	VCC = 3.5 V,	Δ1 = ΔCC 01 QMD			±100		±100		±100	μΛ
$IOZPU^{\ddagger}$ $\frac{V_{CC} = 0 \text{ to } 2}{OE = X}$		$\frac{\text{V}_{C}\text{C}}{\text{OE}} = 0 \text{ to } 2.1 \text{ V, V}_{C}$	y = 0.5 V to 2.7 V,			±50		±50		±50	μА
I_{OZPD}^{\ddagger} $\frac{V_{CC}}{OE} = 2.1 \text{ V to}$		$\frac{\text{V}_{\text{C}}\text{C}}{\text{OE}} = 2.1 \text{ V to } 0, \text{ V}_{\text{C}}$) = 0.5 V to 2.7 V,			±50		±50		±50	μА
I _{OZH} § V ₍		$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			50	S	50		50	μΑ
I _{OZL} §		$V_{CC} = 5.5 V$,	V _O = 0.5 V			-50	Q _C	- 50		- 50	μΑ
l _{off}		V _{CC} = 0,	V_I or $V_O \le 4.5 \text{ V}$			±100	d _d			±100	μΑ
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ
IO¶		$V_{CC} = 5.5 \text{ V},$	V _O = 2.5 V	-50	-100	-225 [#]	-50	-225 [#]	-50	-225#	mA
		V _{CC} = 5.5 V,	Outputs high		1	250		250		250	μΑ
ICC /	A or B ports	$I_{O} = 0$,	Outputs low		24	38		38		38	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μΑ
	Data invests	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5	
Data inputs ΔI _{CC}	Other inputs at V _{CC} or GND	Outputs disabled			1.5#		1.5#		1.5#	mA	
	Control inputs	$V_{CC} = 5.5 \text{ V}$, One in Other inputs at V_{CC}				1.5		1.5		1.5	
C _i (Control inputs	V _I = 2.5 V or 0.5 V			4.5						pF
C _{io} A	A or B ports	V _O = 2.5 V or 0.5 V			10.5						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] This parameter is characterized, but not production tested.

[§] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[¶] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[#]This limit may vary among suppliers.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

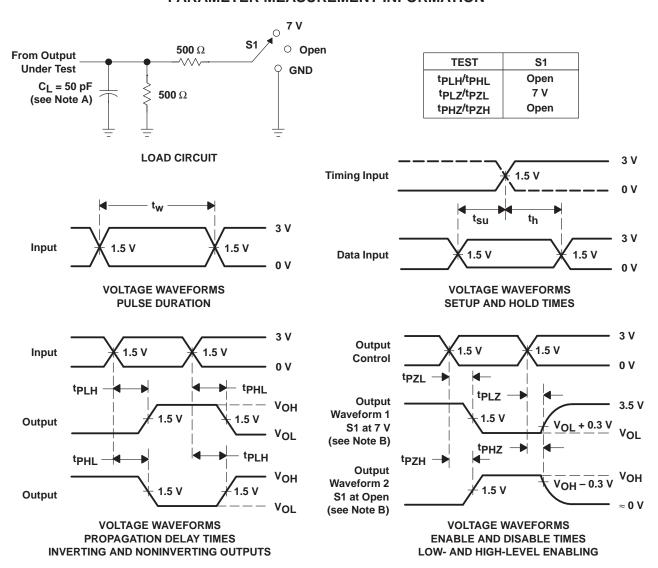
SCBS199C - FEBRUARY 1991 - REVISED MAY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V \(= 25°C	', ;	SN54A	BT861	SN74A	BT861	UNIT
	(INFOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	1	3.4	4.9	1	5.3	1	5.2	ns
tPHL	AOIB	DUIA	1	3.2	4.4	1	5	1	4.9†	115
^t PZH	OEAB or OEBA	B or A	1	3.5	5	1,	6	1	5.9	ns
tPZL	OEAB OF OEBA	BULA	1	4.6	6	37)	7	1	6.9	110
^t PHZ	OF AD an OFDA	B or A	2.1	5.3	6.5	2.1	7.6	2.1	7.5	nc
t _{PLZ}	OEAB or OEBA	D UI A	1.5	5.3	6.6	1.5	7.2	1.5	7.1	ns

[†] This limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \,\Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ABT861DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT861DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT861DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT861DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT861DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT861DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT861NSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT861NSRE4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT861NSRG4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT861NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ABT861NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

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to Customer on an annual basis.	



TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT861DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT861NSR	SO	NS	24	2000	330.0	24.4	8.2	15.4	2.5	12.0	24.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT861DWR	SOIC	DW	24	2000	346.0	346.0	41.0
SN74ABT861NSR	SO	NS	24	2000	346.0	346.0	41.0

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

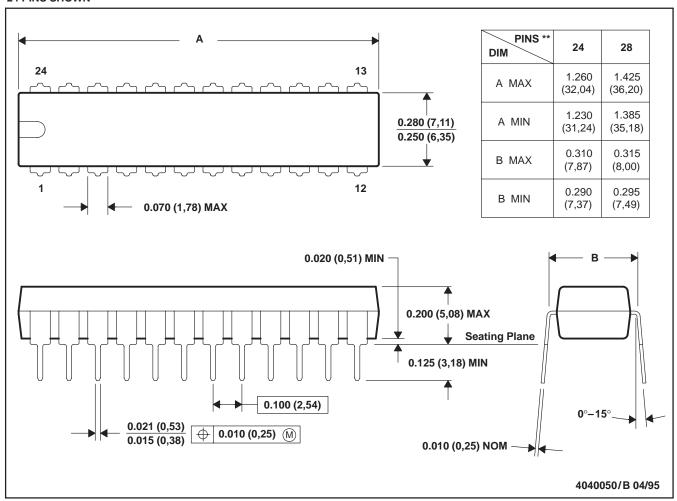
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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